



Transport HX TS75-B8252 / TS75A-B8252

Dual Socket 2U AMD HPC/VM Server Product Overview



World Class Server Platforms

Transport HX TS75-B8252 (12-LFF)

Transport HX TS75-B8252 Product Overview



Server Platform for SDS Applications

The TS75-B8252 is a 2U2S server platform that adopts the latest AMD EPYC 7002 series processor technology and designed for virtualization, containers, and in-memory computing applications. Equipped with 12 front-access 3.5" drive bays, TS75-B8252 provides massive data storage capacity and the 4 of the bays support NVMe U.2 devices for application caching space.

Better Serviceability

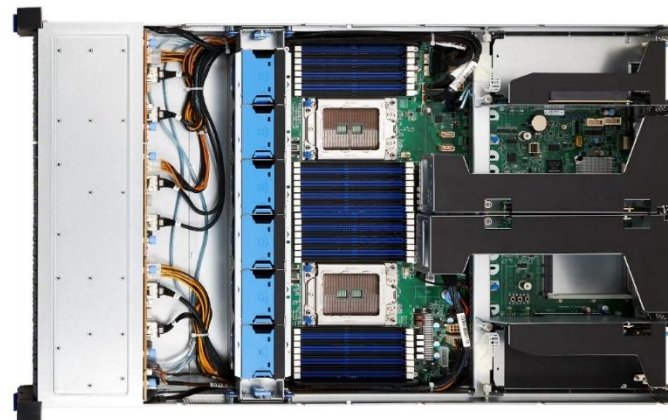
Several new mechanical designs are implemented on TS75-B8252. The new generation of Tyan 3.5" drive carrier is a tool-less design that effectively reduces labor time on drive installation; the quick-released sliding rail kit helps technicians easily install the 2U system onto rack cabinet and the equipped front easy-lock latches can have the servers seated on rack precisely without using a tool.

PCIe Gen. 4.0 x16 OCP 3.0 LAN Mezzanine

Tyan's TS75-B8252 features an PCIe Gen. 4.0 x16 OCP 3.0 LAN mezzanine that provides additional NIC expansion for up to dual 100 Gigabit Ethernet connections.

IPMI 2.0 with Redfish Support

Featuring AMI MegaRAC® firmware, the TS75-B8252 server barebones offers support for IPMI 2.0 with iKVM and the DMTF Redfish management protocol.



TS75A-B8252 top view is used for demonstration purpose

Transport HX TS75-B8252

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2U HPC/VM Server
32-DIMM + 12-LFF

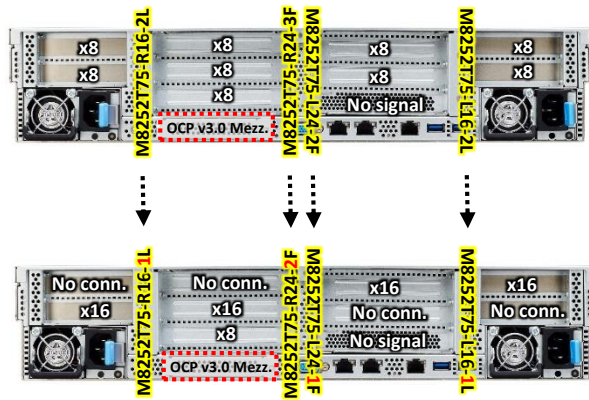


2U EPYC / 32 DIMMs / 12 LFF / 9 PCIe Gen.4 x8 / OCP 3.0 LAN Mezz.

Standard SKUs	Networking	Storage	Max. PCIe slot
B8252T75V8E4HR-8X-2T	(2) 10GBase-T + (1) IPMI	(12) SATA 6G; (4) NVMe U.2	(9) x8 + (1) OCP 3.0 mezz.
B8252T75V8E4HR-2T	(2) 10GBase-T + (1) IPMI	(12) SATA 6G; (4) NVMe U.2	(4) x16 + (1) x8 + (1) OCP 3.0 mezz.



B8252T75V8E4HR-8X-2T Riser Configuration



B8252T75V8E4HR-2T Riser Configuration

■ **2U2S Rome platform supports for up to 32 DIMMs, 2 10GbE onboard LAN, and 1 OCP 3.0 LAN mezzanine slot**

■ **Dimension: H87mm x W438.4mm x D750mm (29.53")**

■ **AMD EPYC™ 7002 Processor w/ cTDP up to 240W**

➤ No support for AMD EPYC™ 7001 processor

■ **Memory**

- (16+16) DDR4 DIMM slots (8x memory channels)
- Support up to 4,096GB RDIMM/LRDIMM DDR4 3200/2933 memory

■ **PCI Expansion Slots**

- (4) FH/10.5"L + (1) FH/HL PCIe [Gen.4](#) x8 slots via 2 risers
- (4) HH/HL PCIe [Gen.4](#) x8 slots via the other 2 risers
- (1) PCIe [Gen.4](#) x16 OCP 3.0 mezz. slot for optional LAN mezz. up to 200Gb/s

■ **Network**

- (2) 10GBase-T LAN ports (Intel® x550-AT2)
- (1) 1000Base-T dedicated IPMI port (Realtek RTL8211E-VB-CG)

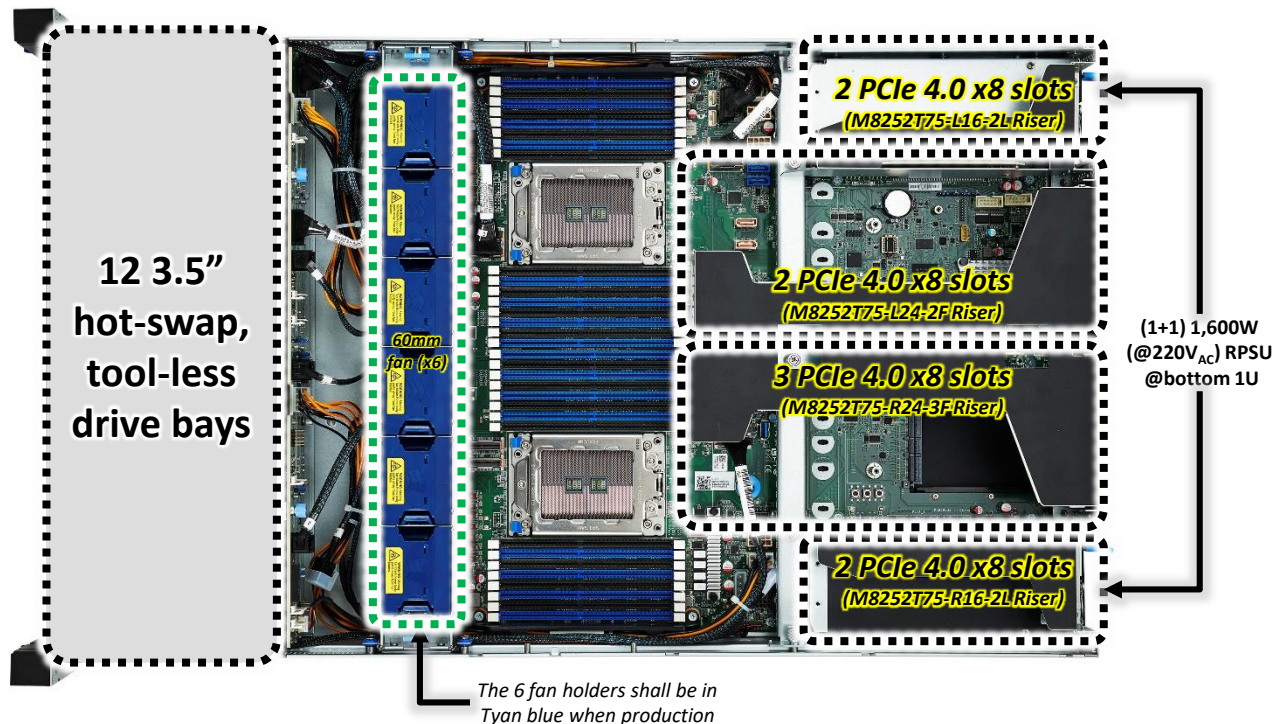
■ **Storage**

- (8) **tool-less**, hot-swap 3.5" SATA 6G devices (from CPU) + (4) **tool-less**, hot-swap NVMe U.2 devices (from CPU)
- (2) 22110/2280 NVMe M.2 slots (PCIe [Gen.4](#) x4 from CPU)

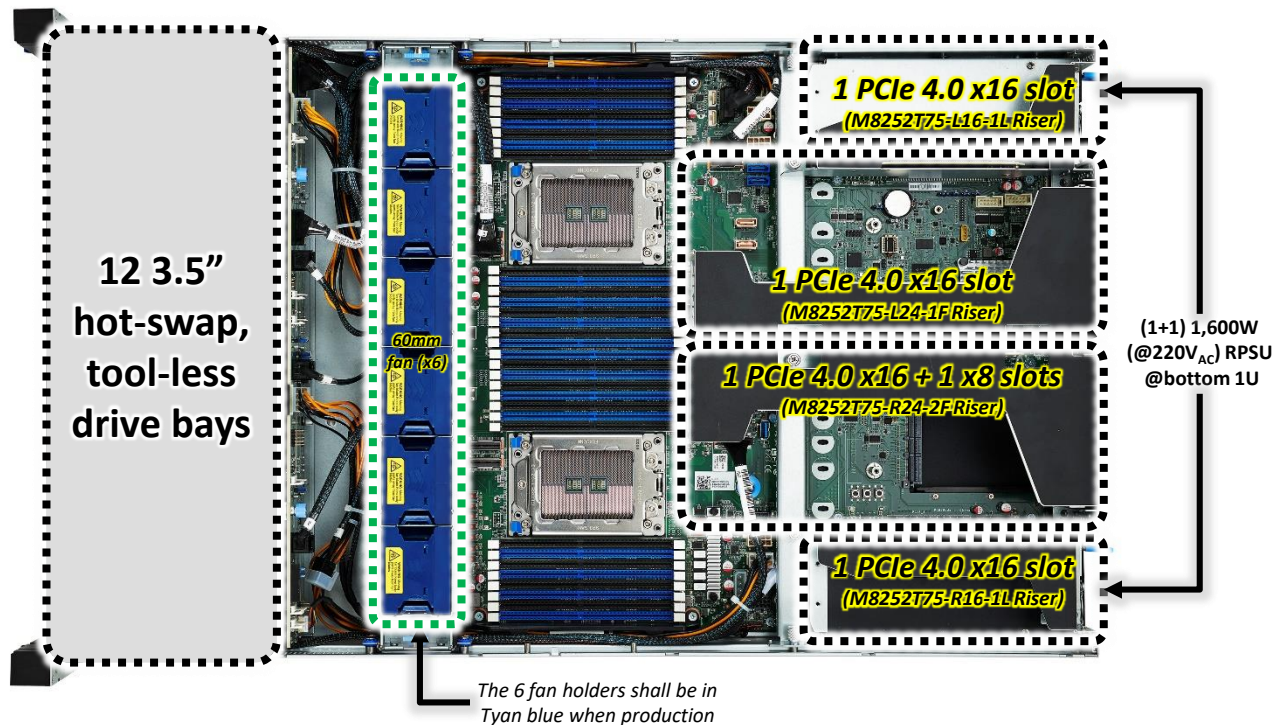
■ **(6) 6038 hot-swap fans**

■ **(1+1) 1,600W hot-swap RPSU @ 220Vac, 80+ Platinum**

Transport HX TS75-B8252 Top View (-8X-2T)

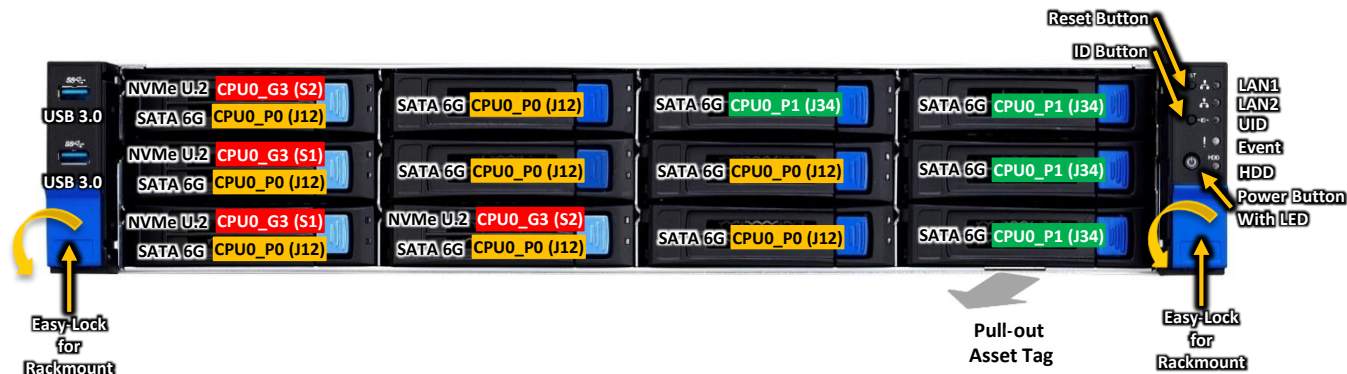


Transport HX TS75-B8252 Top View (-2T)

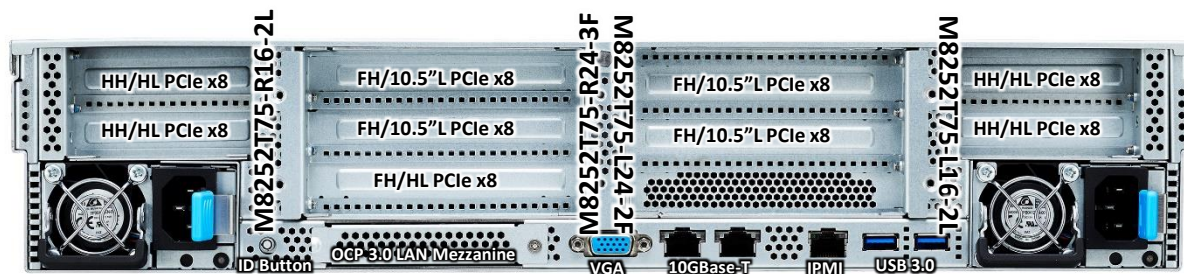


Transport HX TS75-B8252 Views (-8X-2T)

Front

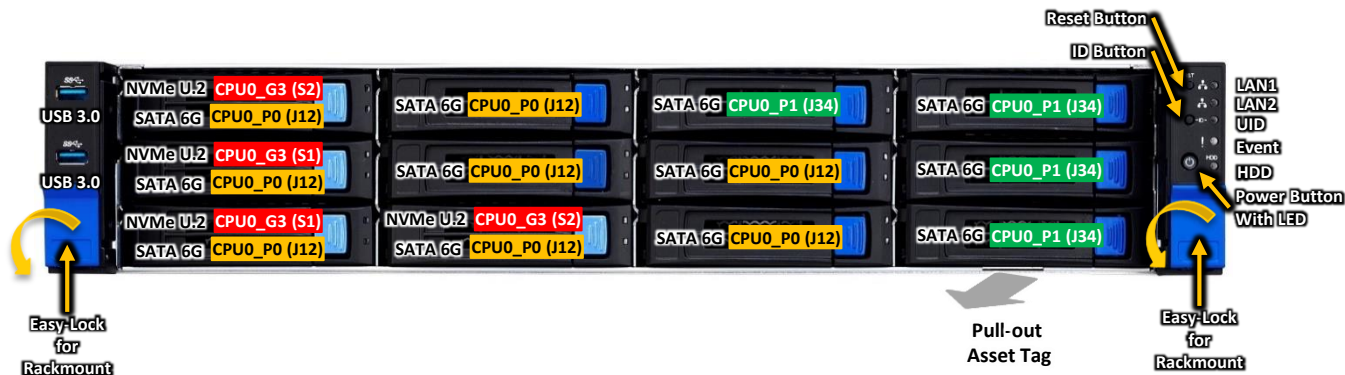


Rear

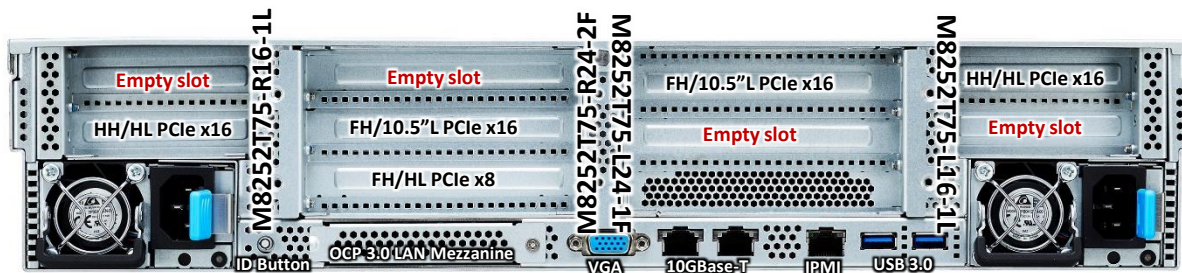


Transport HX TS75-B8252 Views (-2T)

Front



Rear



Transport HX TS75A-B8252 (26-SFF)

Transport HX TS75A-B8252 Product Overview



Server Platform for SDS Applications

The TS75A-B8252 is a 2U2S server platform that adopts the latest AMD EPYC 7002 series processor technology and designed for virtualization, containers, and in-memory computing applications. Equipped with 26 2.5" drive bays, TS75A-B8252 provides multiple spindles for high IOPS real-time storage requirement with huge memory capacity and 8 of the 26 2.5" drive bays can be configured to support NVMe U.2 devices as application caching space.

Better Serviceability

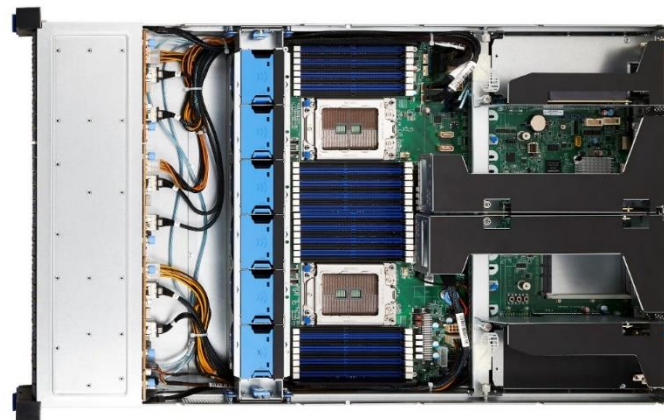
Several new mechanical designs are implemented on TS75A-B8252. The new generation of Tyan 2.5" drive carrier is a tool-less design that effectively reduces labor time on drive installation; the quick-released sliding rail kit helps technicians easily install the 2U system onto rack cabinet and the equipped front easy-lock latches can have the servers seated on rack precisely without using a tool.

PCIe Gen. 4.0 x16 OCP 3.0 LAN Mezzanine

Tyan's TS75A-B8252 features an PCIe Gen. 4.0 x16 OCP 3.0 LAN mezzanine that provides additional NIC expansion for up to dual 100 Gigabit Ethernet connections.

IPMI 2.0 with Redfish Support

Featuring AMI MegaRAC® firmware, the TS75A-B8252 server barebones offers support for IPMI 2.0 with iKVM and the DMTF Redfish management protocol.



Transport HX TS75A-B8252

AVAILABLE
NOW

2U HPC/VM Server
32-DIMM + 12-LFF



2U EPYC / 32 DIMMs / 26 SFF / 9 PCIe Gen.4 x8 / OCP 3.0 LAN Mezz.

Standard SKUs	Networking	Storage	Max. PCIe slot
B8252T75V18E8HR-8X-2T	(2) 10GBase-T + (1) IPMI	(18) SATA 6G + (8) NVMe U.2	(9) x8 + (1) OCP 3.0 mezz.
B8252T75V18E8HR-2T	(2) 10GBase-T + (1) IPMI	(18) SATA 6G + (8) NVMe U.2	(4) x16 + (1) x8 + (1) OCP 3.0 mezz.
B8252T75V26HR-2T	(2) 10GBase-T + (1) IPMI	(26) SATA 6G	(4) x16 + (1) x8 + (1) OCP 3.0 mezz.

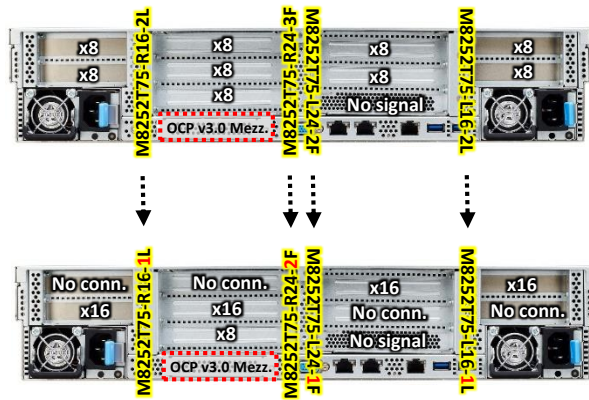


B8252T75AV18E8HR(-8X)-2T



B8252T75AV26HR-2T

B8252T75AV18E4HR-8X-2T Riser Configuration



B8252T75AV18E8HR-2T / B8252T75AV26HR-2T Riser Configuration

- 2U2S Rome platform supports for up to 32 DIMMs, 2 10GbE onboard LAN, and 1 OCP 3.0 LAN mezzanine slot

- Dimension: H87mm x W438.4mm x D750mm (29.53")

- AMD EPYC™ 7002 Processor w/ cTDP up to 240W

- No support for AMD EPYC™ 7001 processor

- Memory

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- Support up to 4,096GB RDIMM/LRDIMM DDR4 3200/2933 memory

- PCI Expansion Slots

- (4) FH/10.5"L + (1) FH/HL PCIe Gen.4 x8 slots via 2 risers
- (4) HH/HL PCIe Gen.4 x8 slots via the other 2 risers
- (1) PCIe Gen.3 x16 OCP 3.0 mezz. slot for optional LAN mezz. up to 200Gb/s

- Network

- (2) 10GBase-T LAN ports (Intel® x550-AT2)
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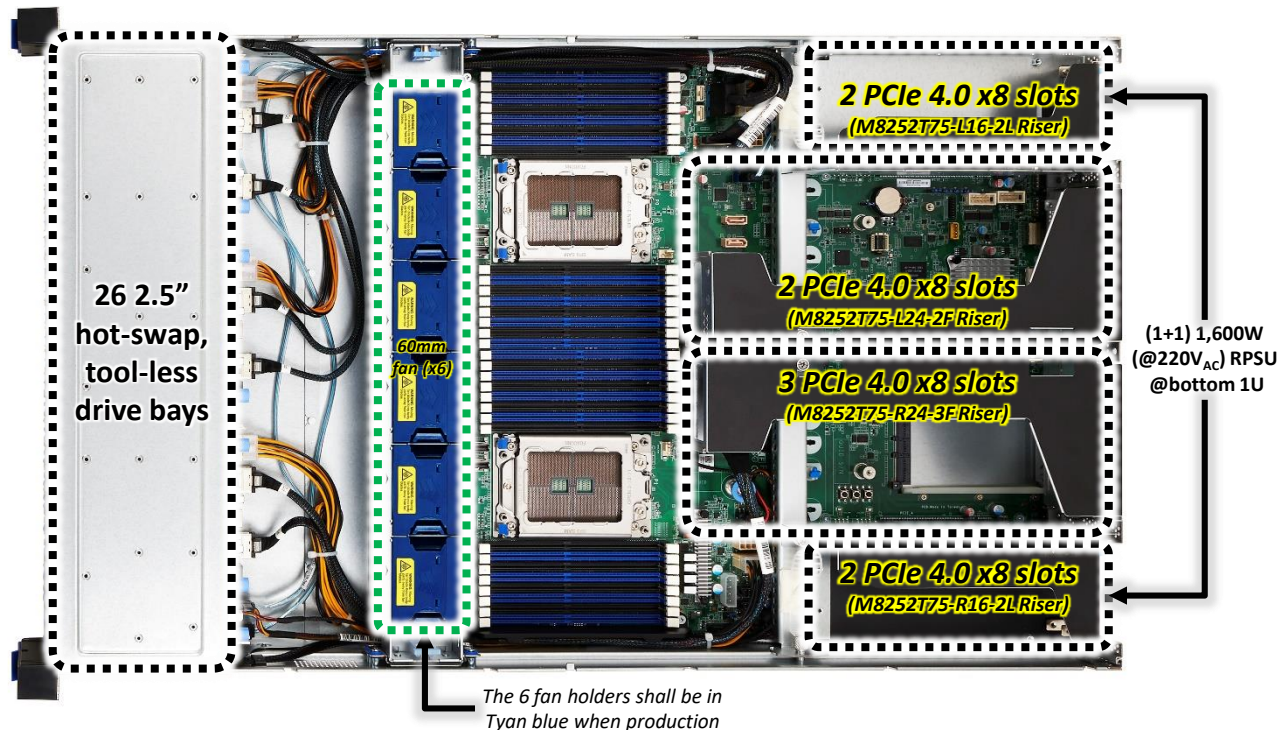
- Storage

- [B8252T75AV26HR-2T] (26) **tool-less**, hot-swap 2.5" SATA 6G devices (24 from CPU, 2 from Marvell SATA IOC)
- [B8252T75AV18E8HR(-8X)-2T] (18) **tool-less**, hot-swap 2.5" SATA 6G devices (16 from CPU, 2 from Marvell SATA IOC) + (8) **tool-less**, hot-swap NVMe U.2 devices (from CPU)
- (2) 22110/2280 NVMe M.2 slots (PCIe Gen.4 x4 from CPU)

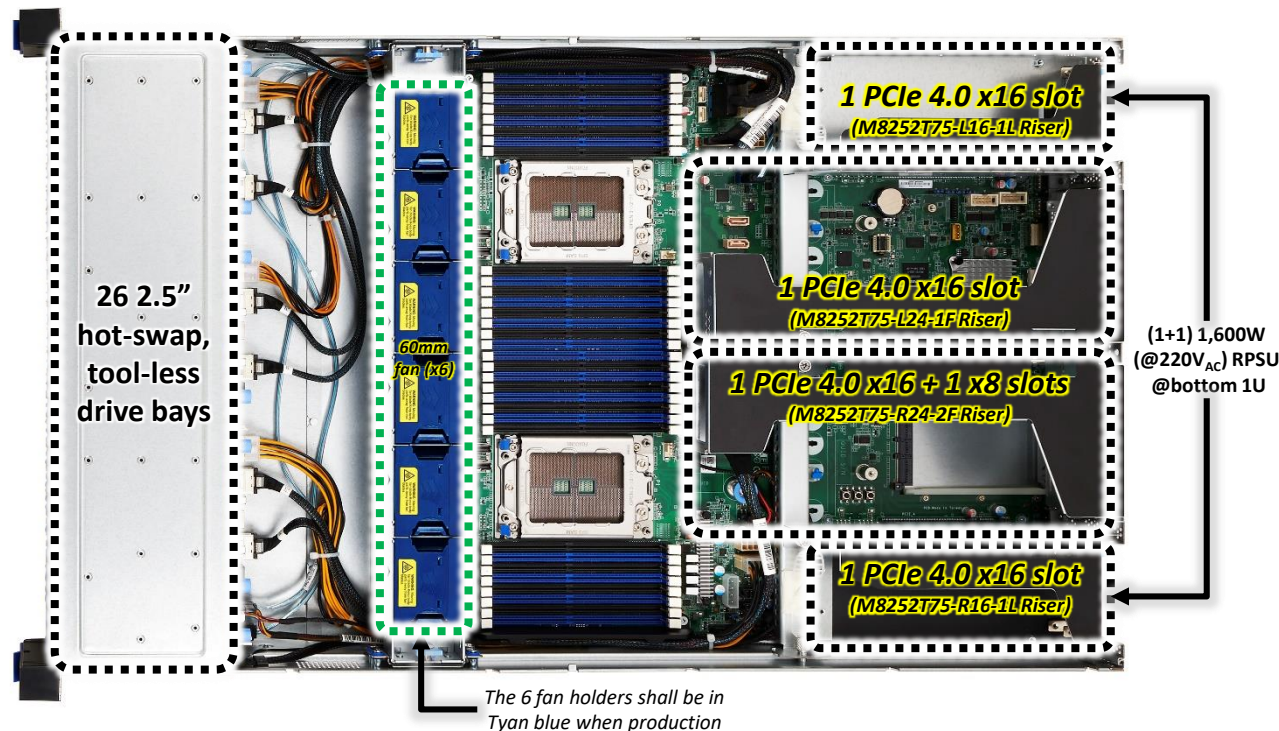
- (6) 6038 hot-swap fans

- (1+1) 1,600W hot-swap RPSU @ 220Vac, 80+ Platinum

Transport HX TS75A-B8252 Top View (-8X-2T)



Transport HX TS75A-B8252 Top View (-2T)

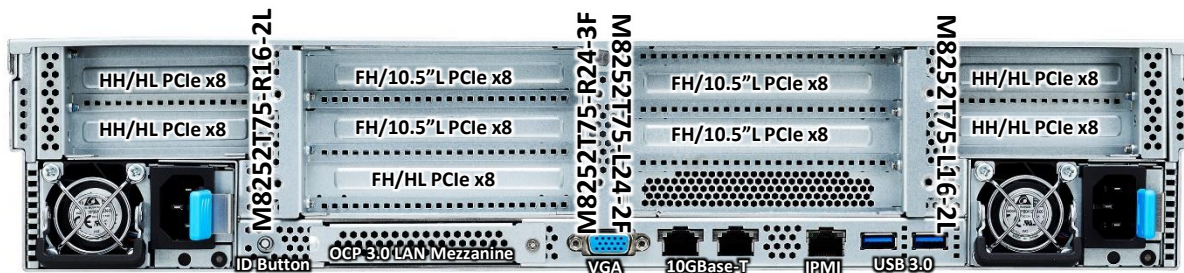


Transport HX TS75A-B8252 Views (-8X-2T)

Front



Rear

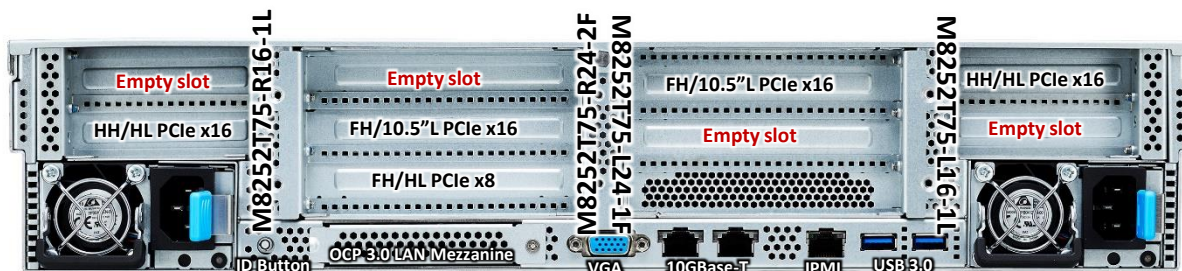


Transport HX TS75A-B8252 Views (-2T)

Front



Rear



THANK YOU